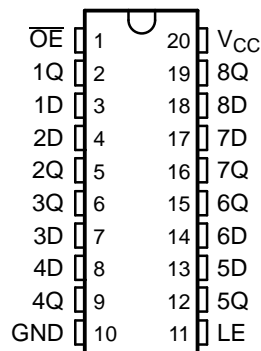


FEATURES

- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3.3 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DG, DW, OR PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This octal transparent D-type latch is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH373 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC - DW	Tube	SN74ALVCH373DW	ALVCH373
		Tape and reel	SN74ALVCH373DWR	
	TSSOP - PW	Tape and reel	SN74ALVCH373PWR	VB373
	TVSOP - DGV	Tape and reel	SN74ALVCH373DGVR	VB373
	VFBGA - GQN	Tape and reel	SN74ALVCH373GQNR	VB373
	VFBGA - ZQN (Pb-free)		SN74ALVCH373ZQNR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

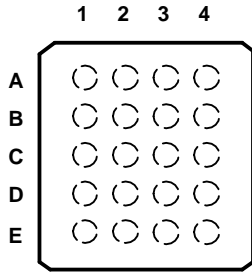


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74ALVCH373 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCES116H—JULY 1997—REVISED OCTOBER 2004

**GQN OR ZQN PACKAGE
(TOP VIEW)**



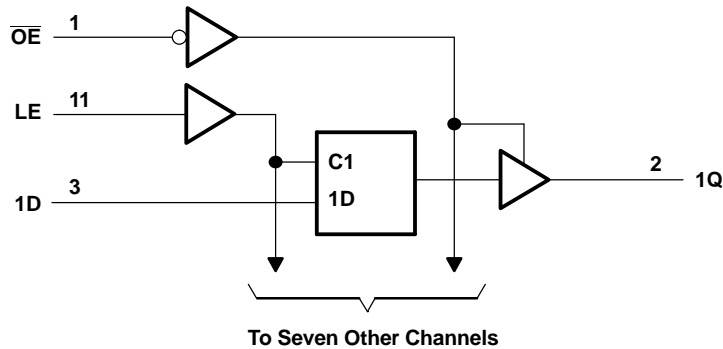
TERMINAL ASSIGNMENTS

	1	2	3	4
A	1Q	\overline{OE}	V_{CC}	8Q
B	2D	7D	1D	8D
C	3Q	2Q	6Q	7Q
D	4D	5D	3D	6D
E	GND	4Q	LE	5Q

**FUNCTION TABLE
(each latch)**

INPUTS			OUTPUT Q
\overline{OE}	LE	D	
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DGV, DW, and PW packages.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	4.6	V
V _I	Input voltage range ⁽²⁾	-0.5	4.6	V
V _O	Output voltage range ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	-50	mA
I _{OK}	Output clamp current	V _O < 0	-50	mA
I _O	Continuous output current		±50	mA
	Continuous current through V _{CC} or GND		±100	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	DGV package	92	°C/W
		DW package	58	
		GQN/ZQN package	78	
		PW package	83	
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	1.7	
		V _{CC} = 2.7 V to 3.6 V	2	
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	0.7	
		V _{CC} = 2.7 V to 3.6 V	0.8	
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	-4	mA
		V _{CC} = 2.3 V	-12	
		V _{CC} = 2.7 V	-12	
		V _{CC} = 3 V	-24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4	mA
		V _{CC} = 2.3 V	12	
		V _{CC} = 2.7 V	12	
		V _{CC} = 3 V	24	
Δt/Δv	Input transition rise or fall rate		5	ns/V
T _A	Operating free-air temperature	-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74ALVCH373
OCTAL TRANSPARENT D-TYPE LATCH
WITH 3-STATE OUTPUTS

SCES116H–JULY 1997–REVISED OCTOBER 2004

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			V
		I _{OH} = -4 mA	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
		I _{OH} = -12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
	I _{OH} = -24 mA	3 V	2				
V _{OL}		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 6 mA	2.3 V			0.4	
		I _{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
I _I		V _I = V _{CC} or GND	3.6 V			±5	μA
I _{I(hold)}		V _I = 0.58 V	1.65 V	25			μA
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	-45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ}		V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			20	μA
ΔI _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	4.5			pF
	Data inputs			5			
C _o	Outputs	V _O = V _{CC} or GND	3.3 V	7.5			pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	3.8		3.3		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	1.3		0.5		0.5		0.5		ns
t _h	Hold time, data after LE↓	0.5		1.3		1.7		1.2		ns

SWITCHING CHARACTERISTICS

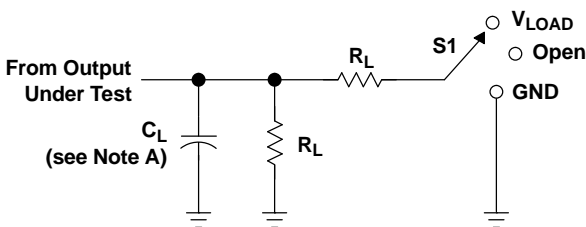
over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	D	Q	1.7	6.3	1	4	4		1	3.6	ns
	LE		2	6.1	1	3.8	3.7		1	3.3	
t_{en}	\overline{OE}	Q	3.4	8.3	1.9	5.4	5.4		1.6	4.8	ns
t_{dis}	\overline{OE}	Q	1.6	7	1	4.4	4.4		1	4.4	ns

OPERATING CHARACTERISTICS
 $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT	
			TYP	TYP	TYP		
C_{pd}	Power dissipation capacitance per latch	Outputs enabled Outputs disabled	$C_L = 0, f = 10\text{ MHz}$	31	33	37	pF
				7	7	9	

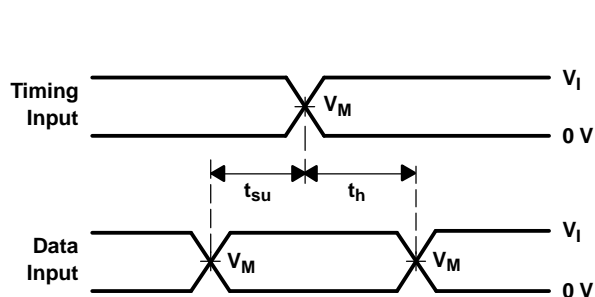
PARAMETER MEASUREMENT INFORMATION



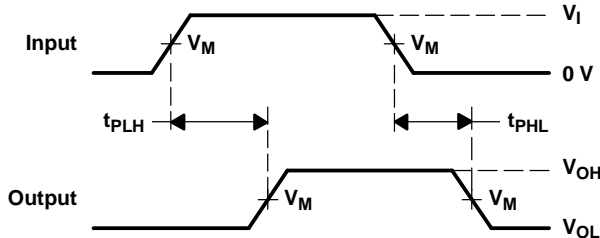
LOAD CIRCUIT

TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open V_{LOAD} GND

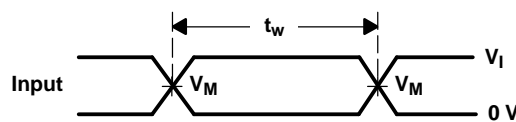
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



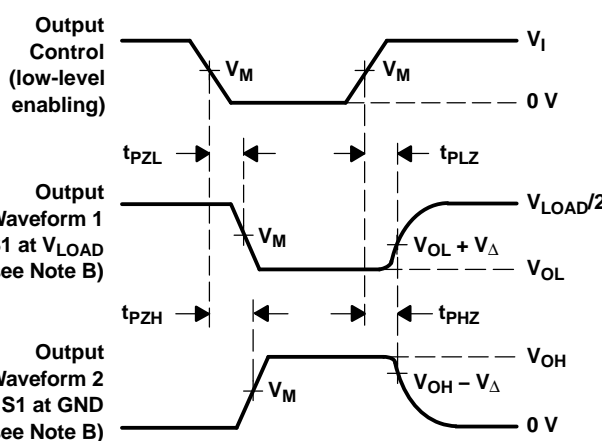
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
74ALVCH373DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVCH373DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH373ZQNR	ACTIVE	BGA MICROSTAR JUNIOR	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH373DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ALVCH373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALVCH373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74ALVCH373ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	330.0	12.4	3.3	4.3	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH373DGVR	TVSOP	DGV	20	2000	367.0	367.0	35.0
SN74ALVCH373DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALVCH373PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74ALVCH373ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	340.5	338.1	20.6

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BC-2.
 - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

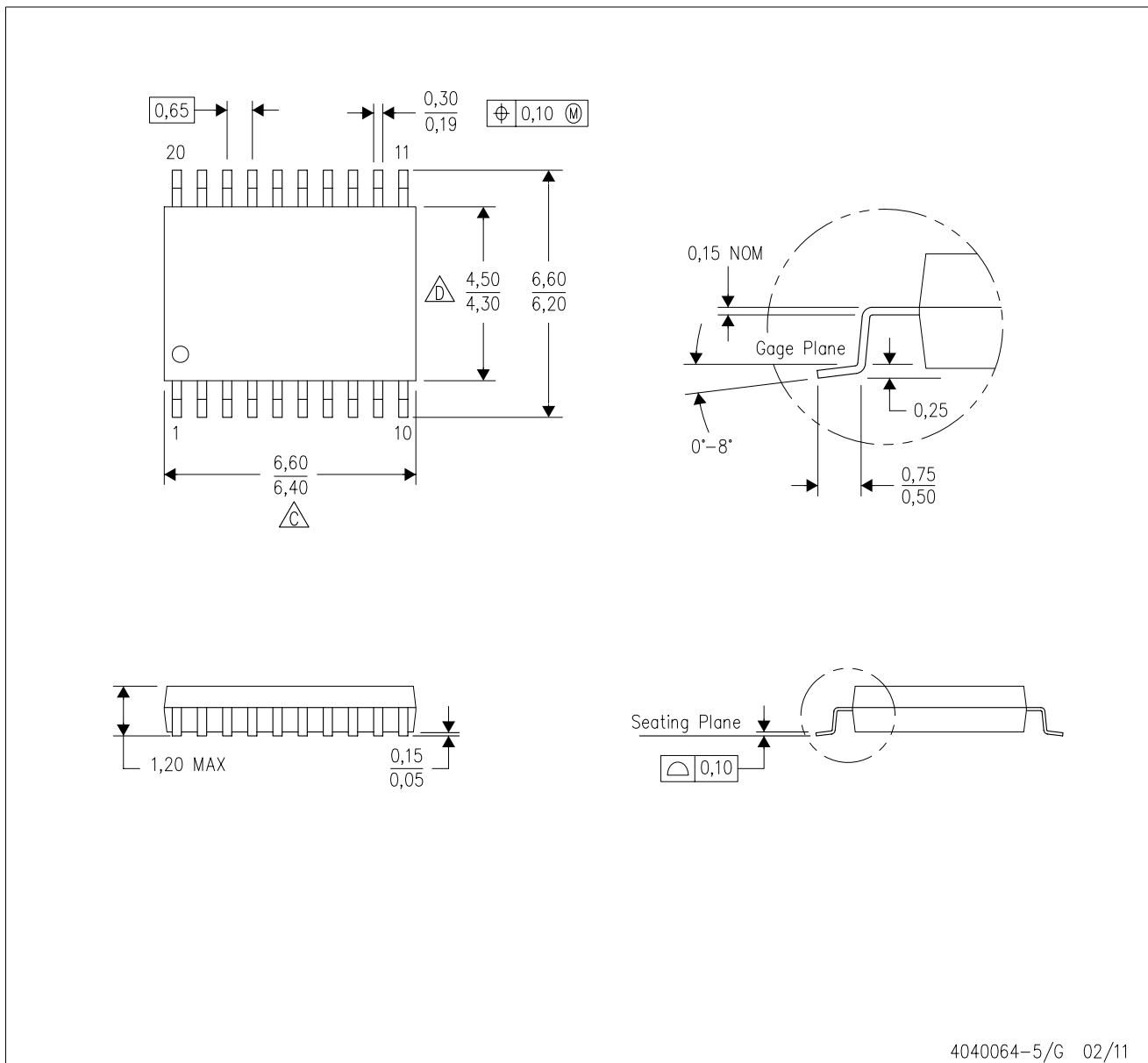
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AC.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

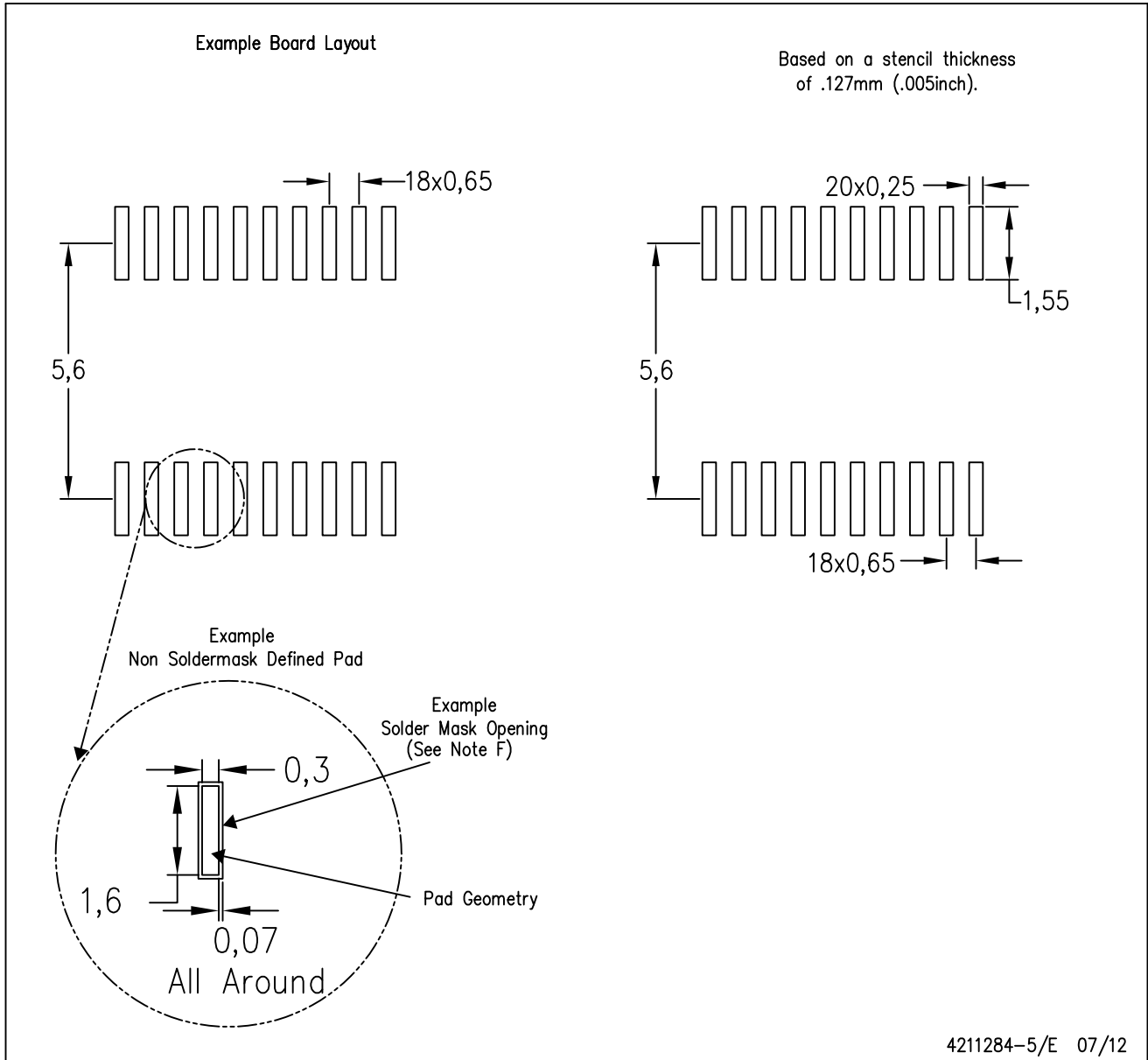


4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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